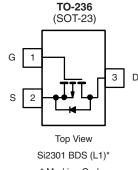


Vishay Siliconix

P-Channel 2.5-V (G-S) MOSFET

PRODUCT SUMMARY			
V _{DS} (V)	R_{DS(on)} (Ω)	I _D (A) ^b	
- 20	0.100 at V _{GS} = - 4.5 V	- 2.4	
	0.150 at V _{GS} = - 2.5 V	- 2.0	



FEATURES

• Halogen-free Option Available



D

* Marking Code

Ordering Information: Si2301BDS-T1 Si2301BDS-T1-E3 (Lead (Pb)-free) Si2301BDS-T1-GE3 (Lead (Pb)-free and Halogen-free)

ABSOLUTE MAXIMUM RATINGS	$T_A = 25 \circ C$, unles	ss otherwise r	noted		
Parameter		Symbol	5 s	Steady State	Unit
Drain-Source Voltage		V _{DS}	- 20		V
Gate-Source Voltage		V _{GS}	± 8		v
Continuous Durin Current (T. 150 °C) ^b	T _A = 25 °C	– I _D -	- 2.4	- 2.2	
Continuous Drain Current (T _J = 150 °C) ^b	T _A = 70 °C		- 1.9	- 1.8	•
Pulsed Drain Current ^a		I _{DM}	- 10		A
Continuous Source Current (Diode Conduction) ^b		۱ _S	- 0.72	- 0.6	
Power Dissipation ^b	T _A = 25 °C	- P _D	0.9	0.7	10/
	T _A = 70 °C		0.57	0.45	W
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150		°C

THERMAL RESISTANCE RATINGS					
Parameter	Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^b	– R _{thJA}	120	145	°C/W	
Maximum Junction-to-Ambient ^c		140	175	C/W	

Notes:

a. Pulse width limited by maximum junction temperature.

b. Surface Mounted on FR4 board, $t \le 5$ s.

c. Surface Mounted on FR4 board.

For SPICE model information via the Worldwide Web: http://www.vishay.com/www/product/spice.htm.

* Pb containing terminations are not RoHS compliant, exemptions may apply.

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SPECIFICATIONS T _J = 25 $^{\circ}$	C, unless c	therwise noted					
Parameter	Symbol		Limits				
		Test Conditions	Min.	Тур.	Max.	Unit	
Static				_	_		
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 V, I_{D} = -250 \mu A$	- 20			v	
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = -250 \ \mu A$	- 0.45		- 0.95	v	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 8 V$			± 100	nA	
Zero Gate Voltage Drain Current		$V_{DS} = -20 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$			- 1	μΑ	
	IDSS	V_{DS} = - 20 V, V_{GS} = 0 V, T_{J} = 55 °C			- 10		
On-State Drain Current ^a		$V_{DS} \leq$ - 5 V, V_{GS} = - 4.5 V	- 6			A	
	I _{D(on)}	$V_{DS} \leq$ - 5 V, V_{GS} = - 2.5 V	- 3				
		$V_{GS} = -4.5 \text{ V}, \text{ I}_{D} = -2.8 \text{ A}$		0.080	0.100	Ω	
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = -2.5 \text{ V}, \text{ I}_{D} = -2.0 \text{ A}$		0.110	0.150		
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 5 V, I _D = - 2.8 A		6.5		S	
Diode Forward Voltage	V _{SD}	$I_{S} = -0.75 \text{ A}, V_{GS} = 0 \text{ V}$		- 0.80	- 1.2	V	
Dynamic ^b			1	1			
Total Gate Charge	Qg			4.5	10	nC	
Gate-Source Charge	Q _{gs}	$V_{DS} = -6 V, V_{GS} = -4.5 V$ $I_{D} \cong -2.8 A$		0.7			
Gate-Drain Charge	Q _{gd}	D = -2.0 A		1.1			
Input Capacitance	C _{iss}			375			
Output Capacitance	C _{oss}	V _{DS} = - 6 V, V _{GS} = 0 V, f = 1 MHz		95		pF	
Reverse Transfer Capacitance	C _{rss}			65			
Switching ^c	· ·		·				
Turn-On Time	t _{d(on)}			20	30	_	
	t _r	$V_{DD} = -6 V, R_L = 6 \Omega$ $I_D \cong -1.0 A, V_{GEN} = -4.5 V$		40	60		
Turn Off Time	t _{d(off)}	$R_{g} = 6 \Omega$		30	45	ns	
Turn-Off Time	t _f	- · · g = • • • •		20	30		

Notes:

a. Pulse test: pulse width \leq 300 μs duty cycle \leq 2 %.

b. For DESIGN AID ONLY, not subject to production testing.

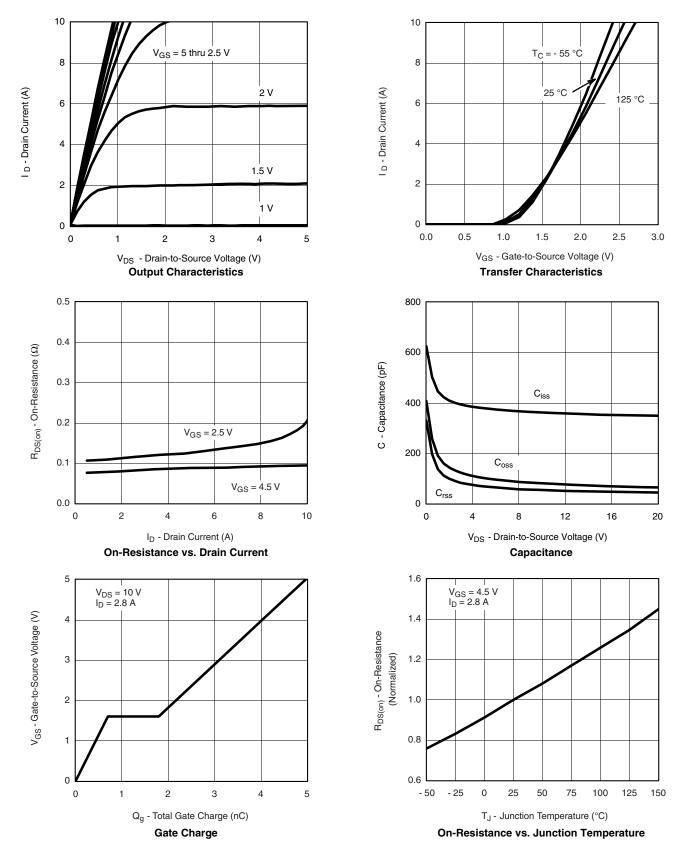
c. Switching time is essentially independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



Si2301BDS Vishay Siliconix

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



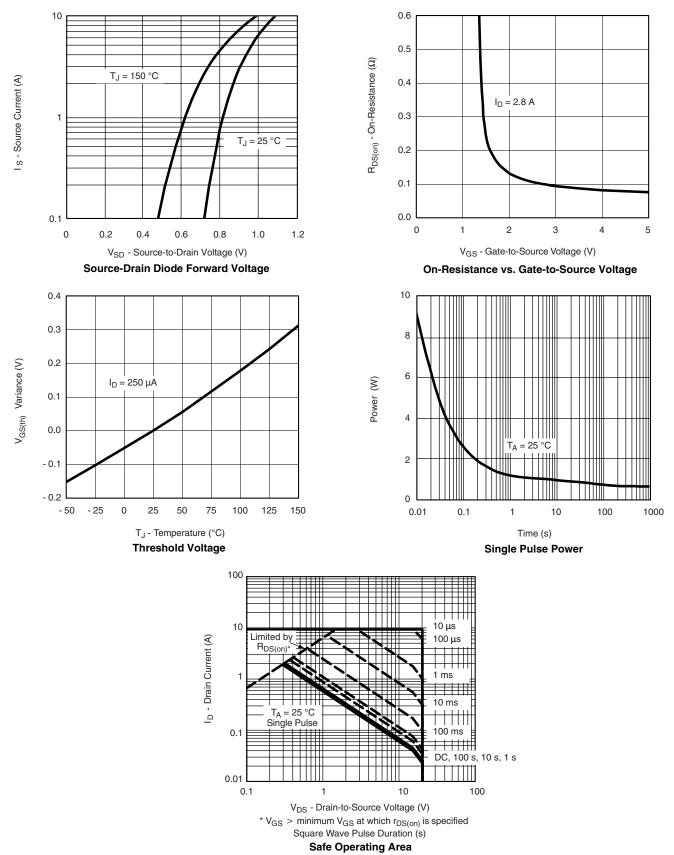
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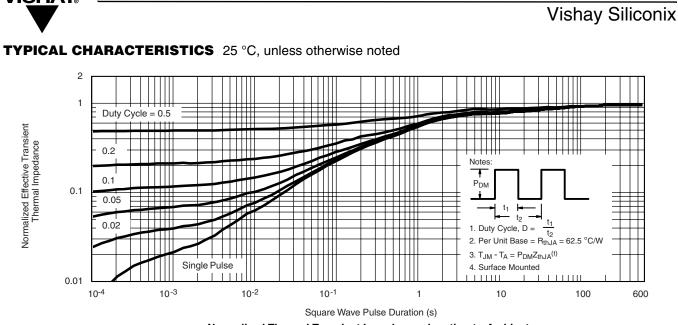
Si2301BDS

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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





Normalized Thermal Transient Impedance, Junction-to-Ambient

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see http://www.vishay.com/ppg?72066.

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Si2301BDS



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